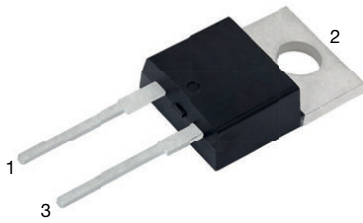
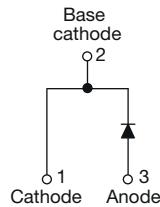


## Ultrafast Rectifier, 8 A FRED Pt<sup>®</sup>



TO-220AC 2L



### FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Designed and qualified according to JEDEC<sup>®</sup>-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### DESCRIPTION / APPLICATIONS

VS-MUR820 is the state of the art ultrafast recovery rectifier specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### PRIMARY CHARACTERISTICS

$I_{F(AV)}$	8 A
$V_R$	200 V
$V_F$ at $I_F$	0.895 V
$t_{rr}$ typ.	See Recovery table
$T_J$ max.	175 °C
Package	TO-220AC 2L
Circuit configuration	Single

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		200	V
Average rectified forward current	$I_{F(AV)}$	Total device, rated $V_R$ , $T_C = 150$ °C	8	A
Non-repetitive peak surge current	$I_{FSM}$		100	
Peak repetitive forward current	$I_{FM}$	Rated $V_R$ , square wave, 20 kHz, $T_C = 150$ °C	16	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

### ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100$ $\mu$ A	200	-	-	V
Forward voltage	$V_F$	$I_F = 8$ A $I_F = 8$ A, $T_J = 150$ °C	-	-	0.975 0.895	
Reverse leakage current	$I_R$	$V_R = V_R$ rated $T_J = 150$ °C, $V_R = V_R$ rated	-	-	5 250	$\mu$ A
Junction capacitance	$C_T$	$V_R = 200$ V	-	25	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH

**DYNAMIC RECOVERY CHARACTERISTICS** ( $T_J = 25\text{ }^\circ\text{C}$  unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $dI_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	-	35	ns	
		$I_F = 0.5\text{ A}$ , $I_R = 1.0\text{ A}$ , $I_{REC} = 0.25\text{ A}$	-	-	25		
		$T_J = 25\text{ }^\circ\text{C}$	-	20	-		
		$T_J = 125\text{ }^\circ\text{C}$	-	34	-		
Peak recovery current	$I_{RRM}$	$I_F = 8\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	$T_J = 25\text{ }^\circ\text{C}$	-	1.7	-	A
			$T_J = 125\text{ }^\circ\text{C}$	-	4.2	-	
Reverse recovery charge	$Q_{rr}$		$T_J = 25\text{ }^\circ\text{C}$	-	23	-	nC
			$T_J = 125\text{ }^\circ\text{C}$	-	75	-	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-65	-	175	$^\circ\text{C}$
Thermal resistance, junction to case	$R_{thJC}$		-	-	3.0	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{thJA}$		-	-	50	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth, and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC 2L	MUR820			

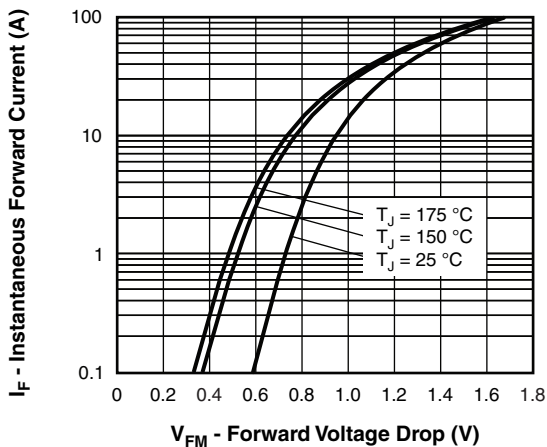


Fig. 1 - Maximum Forward Voltage Drop Characteristics

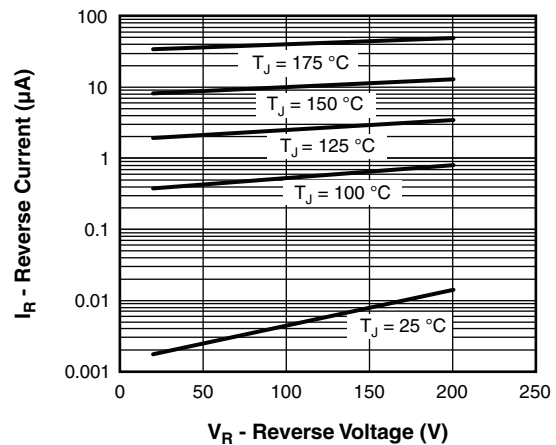


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

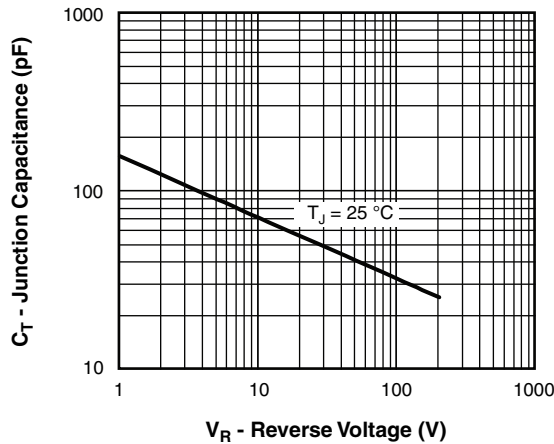


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

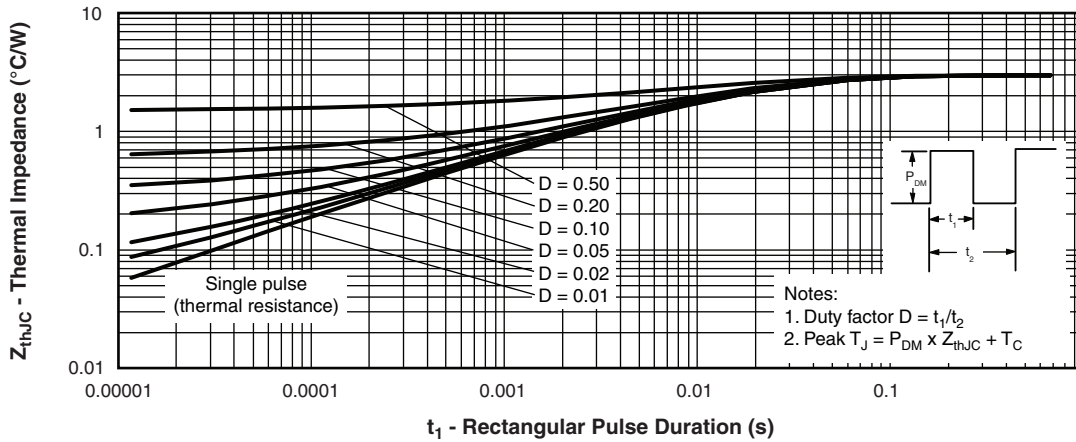


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

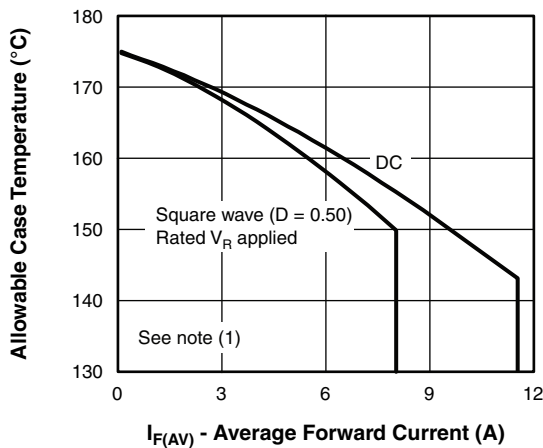


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

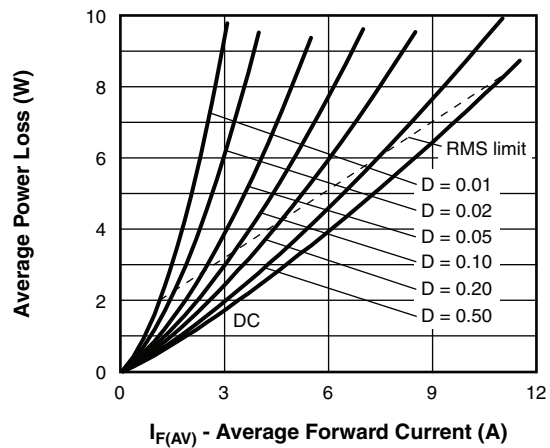


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

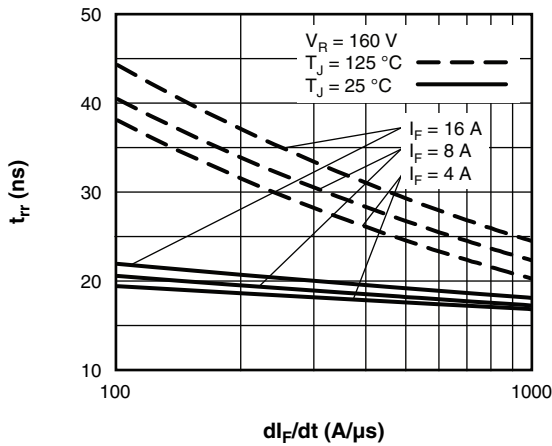


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

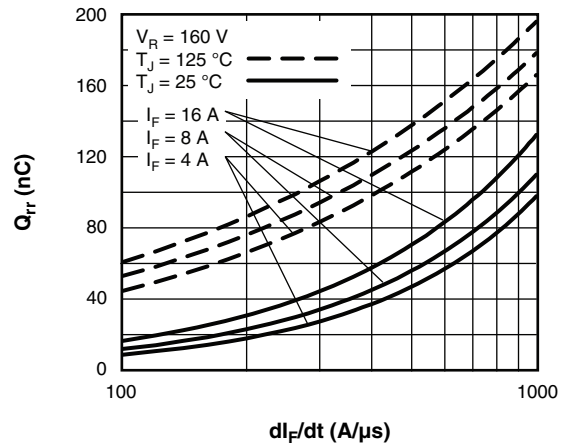


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$

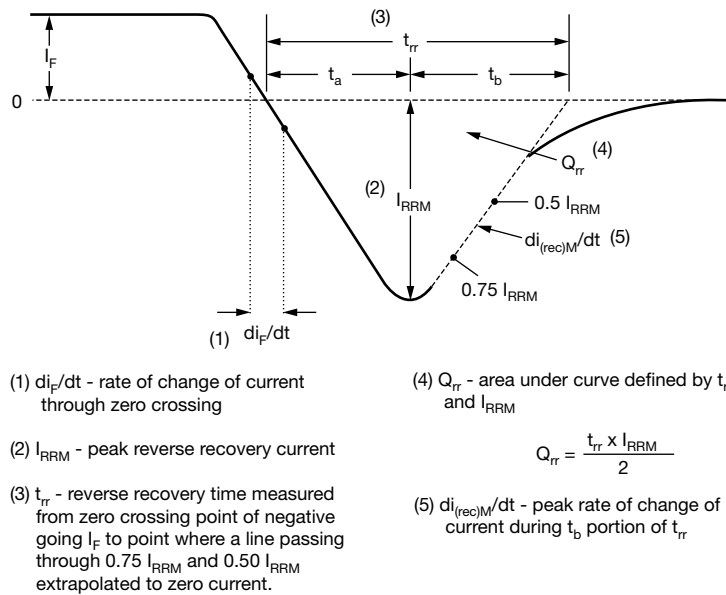
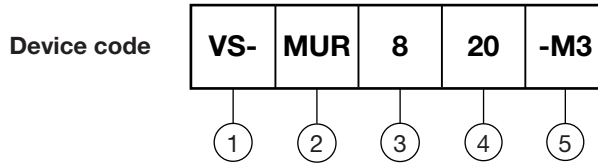


Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Ultrafast MUR series
- 3** - Current rating (8 = 8 A)
- 4** - Voltage rating (20 = 200 V)
- 5** - Environmental digit:  
-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-MUR820-M3	50	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?96156">www.vishay.com/doc?96156</a>
Part marking information	<a href="http://www.vishay.com/doc?95391">www.vishay.com/doc?95391</a>



# 2L TO-220AC

**DIMENSIONS** in millimeters and inches



Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183		D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055		E	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115		E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040		e	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4	e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068		H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4	L	13.52	14.02	0.532	0.552	
c	0.36	0.61	0.014	0.024		L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4	∅ P	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3	Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355							

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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